NTF3055-160

Preferred Device

Power MOSFET 2.0 Amps, 60 Volts N-Channel SOT-223

Designed for low voltage, high speed switching applications in power supplies, converters and power motor controls and bridge circuits.

Applications

- Power Supplies
- Converters
- Power Motor Controls
- Bridge Circuits

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V _{DSS}	60	Vdc
Drain–to–Gate Voltage (R_{GS} = 1.0 M Ω)	VDGR	60	Vdc
Gate–to–Source Voltage – Continuous – Non–repetitive (t _p ≤ 10 ms)	V _{GS}	± 20 ± 30	Vdc Vpk
$\begin{array}{l} \text{Drain Current} \\ - \text{ Continuous @ } T_{A} = 25^{\circ}\text{C} \\ - \text{ Continuous @ } T_{A} = 100^{\circ}\text{C} \\ - \text{ Single Pulse (} t_{p} \leq 10 \ \mu\text{s}) \end{array}$	ID ID IDM	2.0 1.2 6.0	Adc Apk
Total Power Dissipation @ $T_A = 25^{\circ}C$ (Note 1.) Total Power Dissipation @ $T_A = 25^{\circ}C$ (Note 2.) Derate above $25^{\circ}C$	PD	2.1 1.3 0.014	W W W/°C
Operating and Storage Temperature Range	TJ, Tstg	–55 to 175	°C
Single Pulse Drain–to–Source Avalanche Energy – Starting $T_J = 25^{\circ}C$ ($V_{DD} = 25 \text{ Vdc}, V_{GS} = 10 \text{ Vdc},$ $I_L(pk) = 6.0 \text{ Apk}, L = 10 \text{ mH}, V_{DS} = 60 \text{ Vdc})$	E _{AS}	65	mJ
Thermal Resistance – Junction to Ambient (Note 1.) – Junction to Ambient (Note 2.)	R _{θJA} R _{θJA}	72.3 114	°C/W
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	т∟	260	°C

 When surface mounted to an FR4 board using 1" pad size, (Cu. Area 1.127 in²).

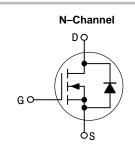
 When surface mounted to an FR4 board using minimum recommended pad size, 2–2.4 oz. (Cu. Area 0.272 in²).

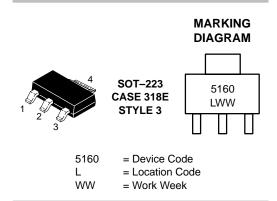


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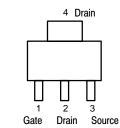
http://onsemi.com

2.0 AMPERES 60 VOLTS RDS(on) = 160 mΩ





PIN ASSIGNMENT



ORDERING INFORMATION

Device	Package	Shipping
NTF3055-160T1	SOT-223	1000 Tape & Reel
NTF3055-160T3	SOT-223	4000 Tape & Reel
NTF3055-160T3LF	SOT-223	4000 Tape & Reel

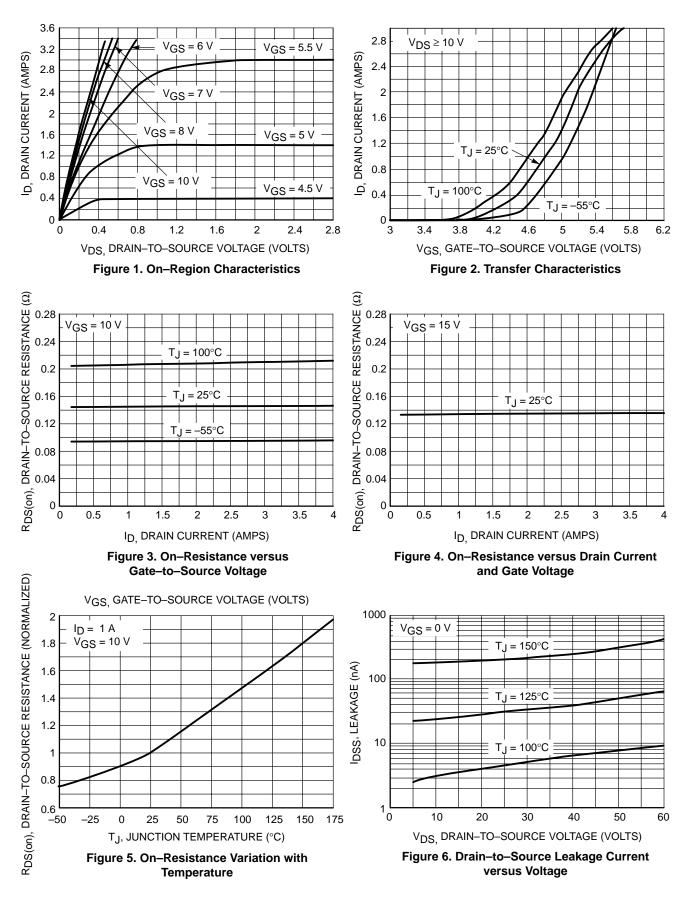
NTF3055-160

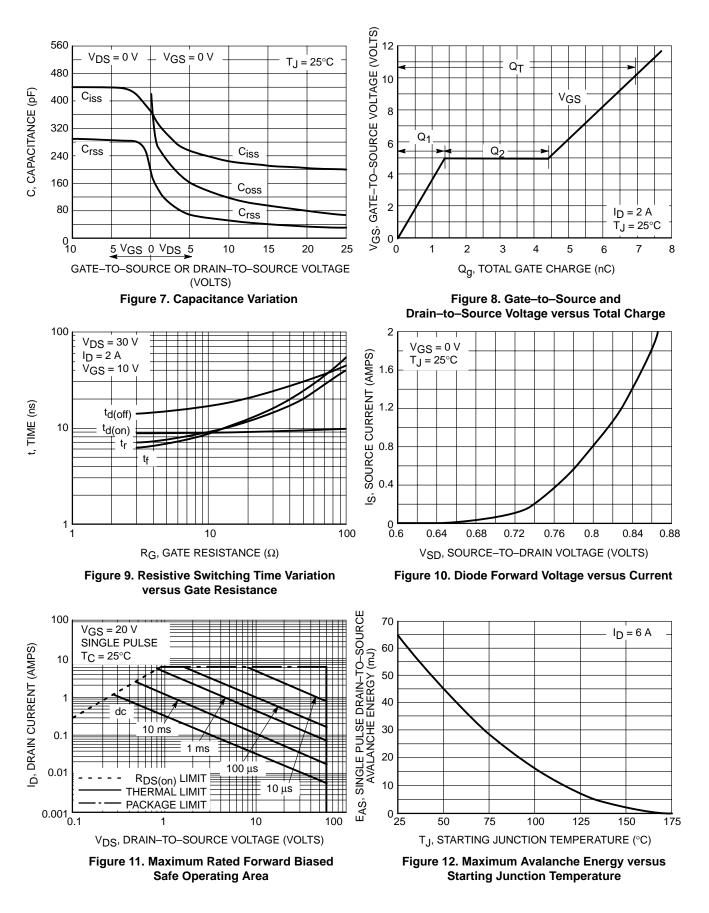
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Charac	Symbol	Min	Тур	Max	Unit	
OFF CHARACTERISTICS						
Drain–to–Source Breakdown Voltage (V _{GS} = 0 Vdc, I _D = 250 μAdc) Temperature Coefficient (Positive)	V(BR)DSS	60 -	72 72		Vdc mV/°C	
Zero Gate Voltage Drain Current ($V_{DS} = 60 \text{ Vdc}, V_{GS} = 0 \text{ Vdc}$) ($V_{DS} = 60 \text{ Vdc}, V_{GS} = 0 \text{ Vdc}, T_J =$	IDSS			1.0 10	μAdc	
Gate–Body Leakage Current (VG	$S = \pm 20$ Vdc, $V_{DS} = 0$ Vdc)	IGSS	_	-	± 100	nAdc
ON CHARACTERISTICS (Note 3.)						•
Gate Threshold Voltage (Note 3.) ($V_{DS} = V_{GS}$, $I_D = 250 \ \mu Adc$) Threshold Temperature Coefficient (N	VGS(th)	2.0	3.1 6.6	4.0 -	Vdc mV/°C	
Static Drain–to–Source On–Resistan (V _{GS} = 10 Vdc, I _D = 1.0 Adc)	R _{DS(on)}	_	142	160	mΩ	
Static Drain-to-Source On-Resistan (V _{GS} = 10 Vdc, I _D = 2.0 Adc) (V _{GS} = 10 Vdc, I _D = 1.0 Adc, T _J =	VDS(on)	_	0.142 0.270	0.384 -	Vdc	
Forward Transconductance (Note 3.)	9fs	_	1.8	-	Mhos	
DYNAMIC CHARACTERISTICS						•
Input Capacitance		C _{iss}	-	200	280	pF
Output Capacitance	(V _{DS} = 25 Vdc, V _{GS} = 0 V, f = 1.0 MHz)	C _{oss}	_	68	100	
Transfer Capacitance	1 – 1.0 Will2)	C _{rss}	_	26	40	
SWITCHING CHARACTERISTICS	S (Note 4.)					•
Turn-On Delay Time		^t d(on)	-	9.2	20	ns
Rise Time	$(V_{DD} = 30 \text{ Vdc}, I_D = 2.0 \text{ Adc},$	tr	_	9.2	20	
Turn–Off Delay Time	V _{GS} = 10 Vdc, R _G = 9.1 Ω) (Note 3.)	^t d(off)	_	16	40	
Fall Time		t _f	-	9.2	20	
Gate Charge		QT	-	6.9	14	nC
	(V _{DS} = 48 Vdc, I _D = 2.0 Adc, V _{GS} = 10 Vdc) (Note 3.)	Q ₁	-	1.4	-	
		Q ₂	-	3.0	-	
SOURCE-DRAIN DIODE CHARA	CTERISTICS					
Forward On–Voltage	$(I_S = 2.0 \text{ Adc}, V_{GS} = 0 \text{ Vdc})$ $(I_S = 2.0 \text{ Adc}, V_{GS} = 0 \text{ Vdc},$ $T_J = 150^{\circ}\text{C})$ (Note 3.)	V _{SD}		0.86 0.70	1.0 _	Vdc
Reverse Recovery Time		t _{rr}	_	28.9	_	ns
	(I _S = 2.0 Adc, V _{GS} = 0 Vdc,	ta	_	19.1	_	
	$dI_{S}/dt = 100 \text{ A}/\mu \text{s}$ (Note 3.)	tb	_	9.8	-	
Reverse Recovery Stored Charge		Q _{RR}	-	0.030	-	μC

3. Pulse Test: Pulse Width \leq 300 µs, Duty Cycle \leq 2.0%.

4. Switching characteristics are independent of operating junction temperatures.





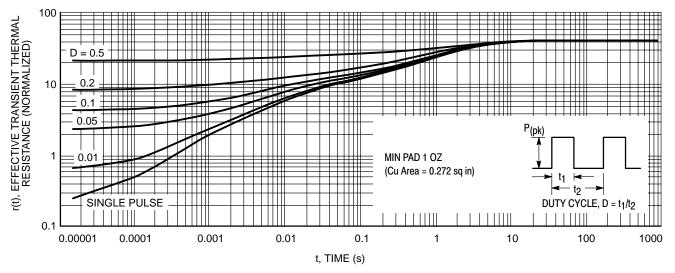
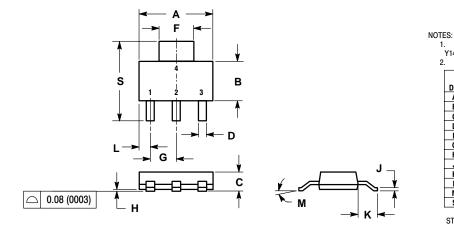


Figure 13. Thermal Response

PACKAGE DIMENSIONS

SOT-223 (TO-261) CASE 318E-04 ISSUE K



NOIL	_0.						
1.	1. DIMENSIONING AND TOLERANCING PER ANSI						
	Y14.5	M, 1982.					
2.	. CO	NTROLLI	NG DIMEI	NSION: IN	ICH.		
1							
		INCHES		MILLIMETERS			
	DIM	MIN	MAX	MIN	MAX		
	Α	0.249	0.263	6.30	6.70		
	В	0.130	0.145	3.30	3.70		
	С	0.060	0.068	1.50	1.75		
	D	0.024	0.035	0.60	0.89		
	F	0.115	0.126	2.90	3.20		
	-						

STYLE 3: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

<u>Notes</u>

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